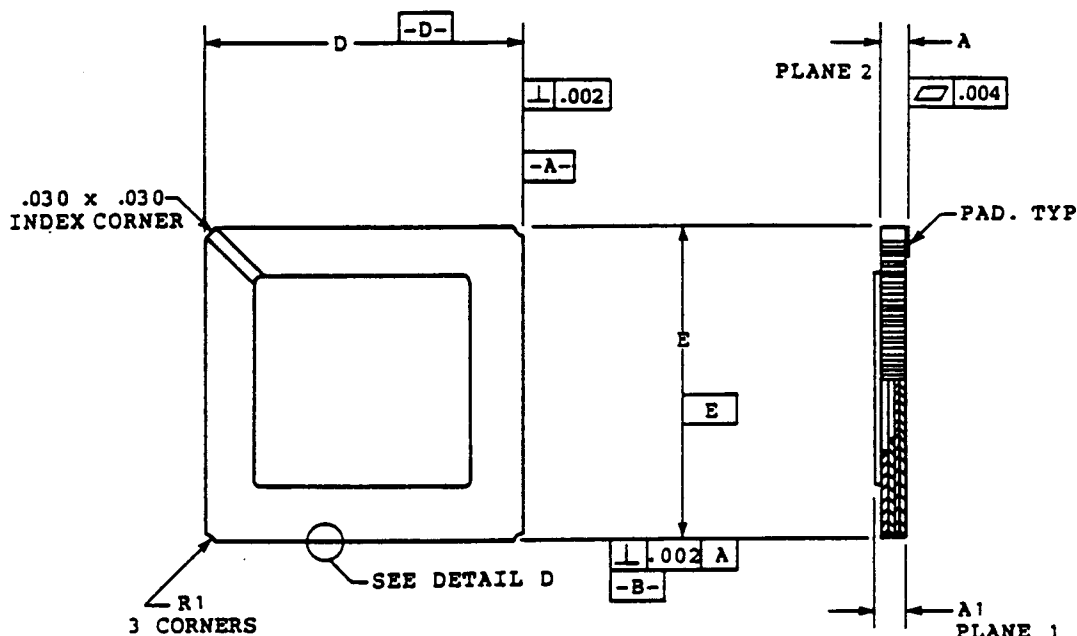
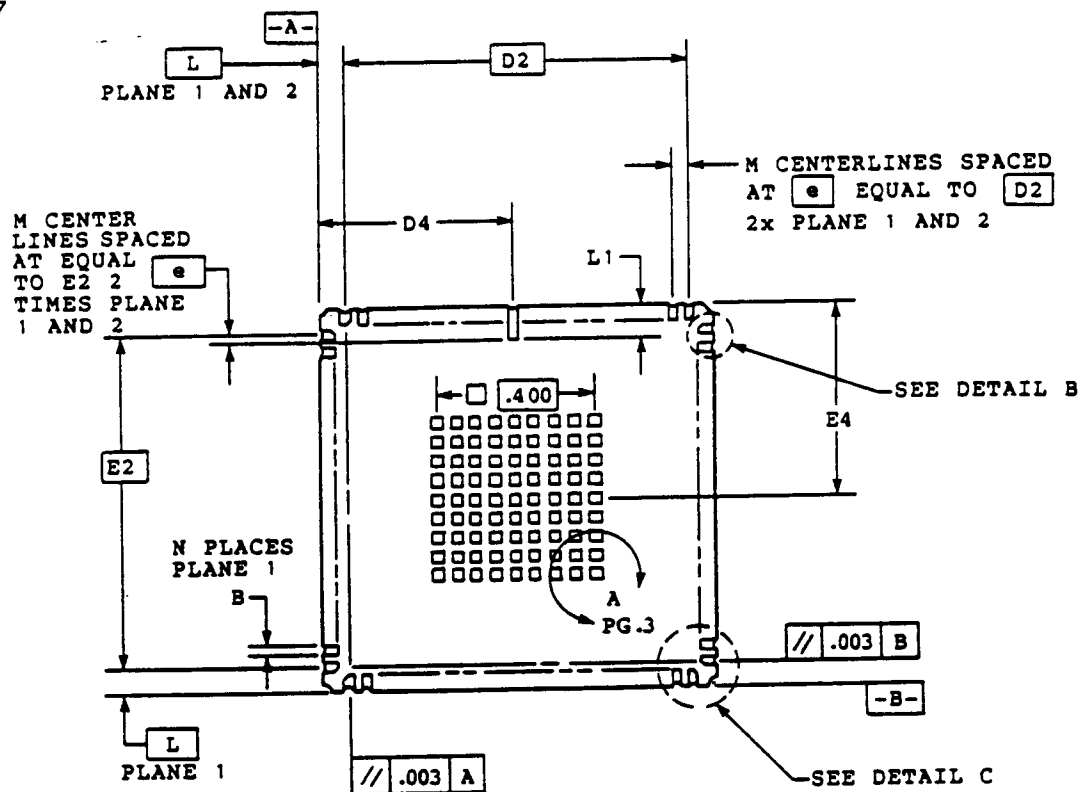


MO-062

.025 CENTER
CERAMIC
CHIP CARRIER

REGISTRATION



VARIATIONS

S Y M B O L	AA				S Y M B O L	AA					
	Millimeters		N O T E			Inches		N O T E			
	MIN	MAX		MIN		MAX	MIN		MAX	MIN	MAX
A	1.70	2.06	6 5		A	.067	.081	6 5			
A1	2.01	2.36			A1	.079	.093				
A2					A2						
B	.229	.305			B	.009	.012				
D	25.273	25.527			D	.995	1.005				
D1	22.860	BSC			D2	.900	BSC				
D4	12.700	REF			D4	.500	REF				
D5	22.90	23.75			D5	.905	.935				
E	25.273	25.529			E	.995	1.005				
E1					E1						
E2	22.860	BSC			E2	.900	BSC				
E4	12.700	REF			E4	.500	REF				
E5					E5						
e	.635	BSC			e	.025	BSC				
L	1.27	BSC			L	.050	BSC				
L1	1.65	2.67			L1	.065	.105				
M		37			M		37				
N		148			N		148				
P					P						
R1	.127	MAX			R	.005	MAX				
S			S								
T			T								
T1			T1								
NOTE 1,2,3											
REF ITEM 10.235											

- NOTES:
1. Dimensioning and tolerancing per ANS/Y14.5 M1982
 2. Controlling dimension: inch
 3. Plane 1 is heat radiating surface.
 4. MAX. DIMENSION INCLUDES ALL METALIZATION
 5. N is the maximum quantity of terminal positions.
Refer to numbering convention.
 6. M is the number of terminal positions on one edge
of the package.

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE: CERAMIC .025 CENTER CHIP CARRIER REGISTRATION	ISSUE A	DATE 4/2/87	MO-062
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